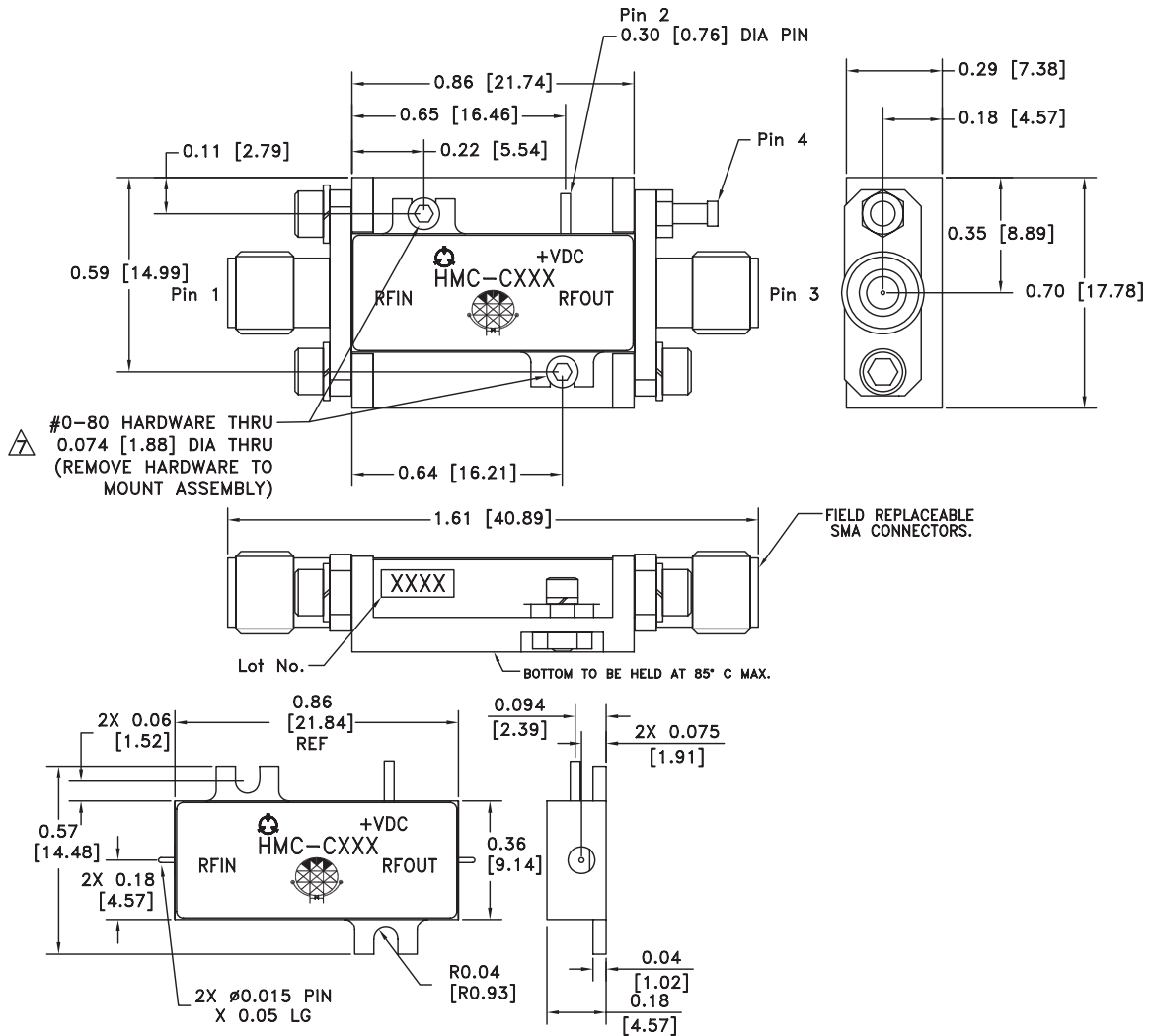


C-3 – CONNECTORIZED HERMETIC MODULE

C-3 Package Outline Drawing



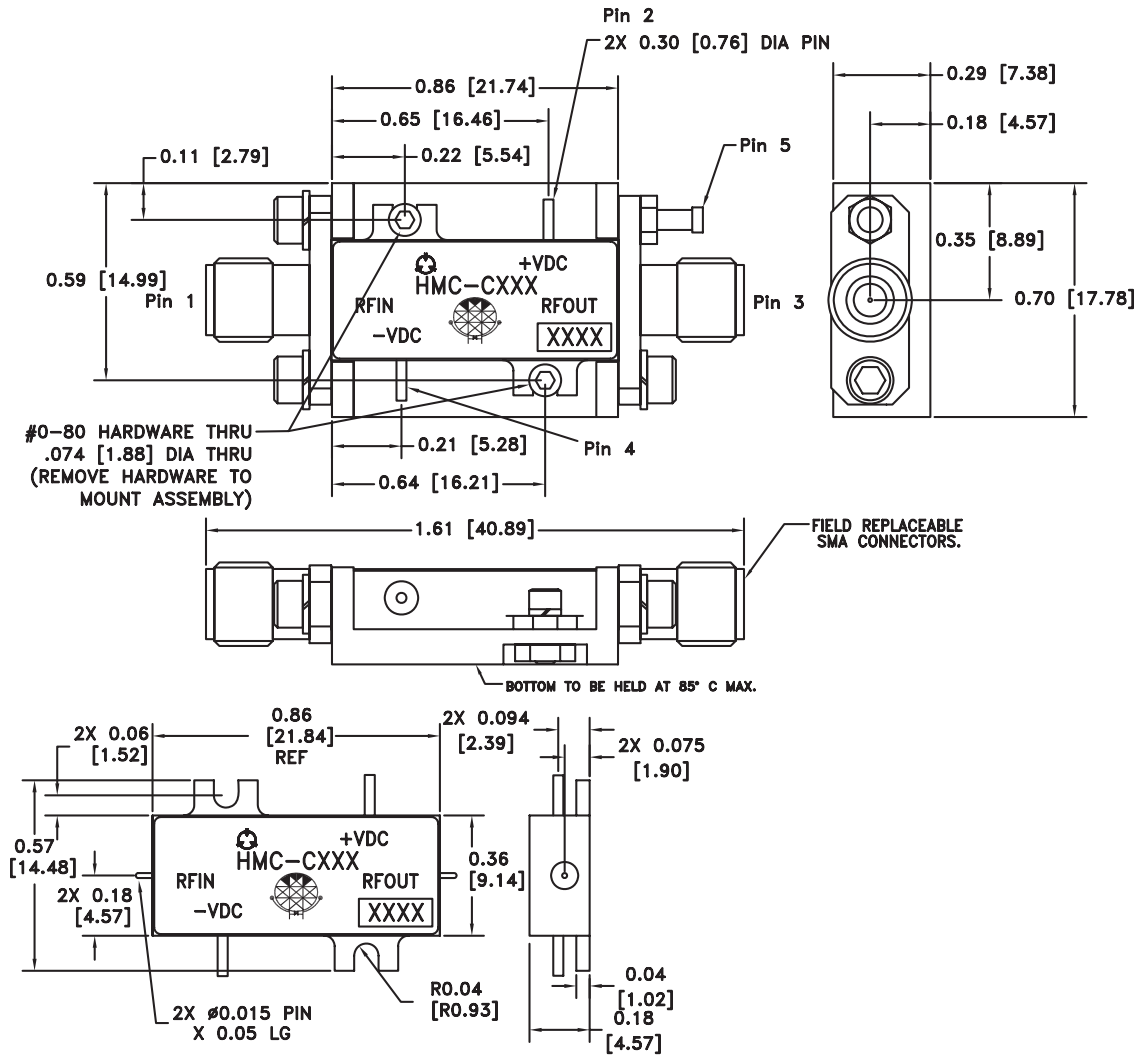
NOTES:

1. PACKAGE, LEADS, COVER MATERIAL: KOVAR™
 2. SPACER MATERIAL: ALUMINUM
 3. PLATING: ELECTROLYTIC GOLD 50 MICROINCHES MIN., OVER ELECTROLYTIC NICKEL 75 MICROINCHES MIN.
 4. ALL DIMENSIONS ARE IN INCHES [MILLIMETERS].
 5. TOLERANCES ±.005 [0.13] UNLESS OTHERWISE SPECIFIED.
 6. FIELD REPLACEABLE SMA CONNECTORS.
TENSOLITE 5602 - 5CCSF OR EQUIVALENT.
- △ TO MOUNT MODULE TO SYSTEM PLATFORM REPLACE 0-80 HARDWARE WITH DESIRED MOUNTING SCREWS.



**C-3B – CONNECTORIZED
HERMETIC MODULE**

C-3B Package Outline Drawing



NOTES:

1. PACKAGE, LEADS, COVER MATERIAL: KOVAR™
 2. SPACER MATERIAL: ALUMINUM
 3. PLATING: ELECTROLYTIC GOLD 50 MICROINCHES MIN., OVER ELECTROLYTIC NICKEL 75 MICROINCHES MIN.
 4. ALL DIMENSIONS ARE IN INCHES [MILLIMETERS].
 5. TOLERANCES ±.005 [0.13] UNLESS OTHERWISE SPECIFIED.
 6. FIELD REPLACEABLE SMA CONNECTORS.
- TENSOLITE 5602 - 5CCSF OR EQUIVALENT.
- △ TO MOUNT MODULE TO SYSTEM PLATFORM REPLACE 0-80 HARDWARE WITH DESIRED MOUNTING SCREWS.